

FQD11P06 / FQU11P06

60V P-Channel MOSFET

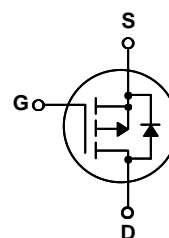
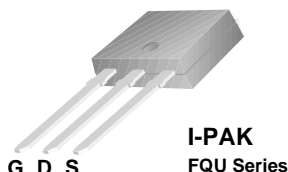
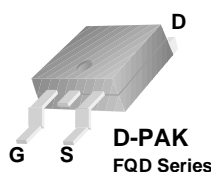
General Description

These P-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand a high energy pulse in the avalanche and commutation modes. These devices are well suited for low voltage applications such as automotive, DC/DC converters, and high efficiency switching for power management in portable and battery operated products.

Features

- -9.4A, -60V, $R_{DS(on)} = 0.185\Omega @ V_{GS} = -10V$
- Low gate charge (typical 13 nC)
- Low Crss (typical 45 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability



Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter	FQD11P06 / FQU11P06	Units
V _{DSS}	Drain-Source Voltage	-60	V
I _D	Drain Current - Continuous (T _C = 25°C) - Continuous (T _C = 100°C)	-9.4	A
		-5.95	A
I _{DM}	Drain Current - Pulsed (Note 1)	-37.6	A
V _{GSS}	Gate-Source Voltage	± 30	V
E _{AS}	Single Pulsed Avalanche Energy (Note 2)	160	mJ
I _{AR}	Avalanche Current (Note 1)	-9.4	A
E _{AR}	Repetitive Avalanche Energy (Note 1)	3.8	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	-7.0	V/ns
P _D	Power Dissipation (T _A = 25°C) *	2.5	W
	Power Dissipation (T _C = 25°C) - Derate above 25°C	38	W
		0.3	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +150	°C
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	°C

Thermal Characteristics

Symbol	Parameter	Typ	Max	Units
R _{θJC}	Thermal Resistance, Junction-to-Case	--	3.28	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient *	--	50	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient	--	110	°C/W

* When mounted on the minimum pad size recommended (PCB Mount)

Elerical Characteristics

$T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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Off Characteristics

BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = -250\ \mu\text{A}$	-60	--	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = -250\ \mu\text{A}$, Referenced to 25°C	--	-0.07	--	V/ $^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -60\text{ V}, V_{GS} = 0\text{ V}$	--	--	-1	μA
		$V_{DS} = -48\text{ V}, T_C = 125^\circ\text{C}$	--	--	-10	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = -25\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = 25\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\ \mu\text{A}$	-2.0	--	-4.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = -10\text{ V}, I_D = -4.7\text{ A}$	--	0.15	0.185	Ω
g_{FS}	Forward Transconductance	$V_{DS} = -30\text{ V}, I_D = -4.7\text{ A}$ (Note 4)	--	4.9	--	S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = -25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$	--	420	550	pF
C_{oss}	Output Capacitance		--	195	250	pF
C_{rss}	Reverse Transfer Capacitance		--	45	60	pF

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = -30\text{ V}, I_D = -5.7\text{ A},$ $R_G = 25\ \Omega$	--	6.5	25	ns	
t_r	Turn-On Rise Time		--	40	90	ns	
$t_{d(off)}$	Turn-Off Delay Time		(Note 4, 5)	--	15	40	ns
t_f	Turn-Off Fall Time		(Note 4, 5)	--	45	100	ns
Q_g	Total Gate Charge	$V_{DS} = -48\text{ V}, I_D = -11.4\text{ A},$ $V_{GS} = -10\text{ V}$	--	13	17	nC	
Q_{gs}	Gate-Source Charge		(Note 4, 5)	--	2.0	--	nC
Q_{gd}	Gate-Drain Charge		(Note 4, 5)	--	6.3	--	nC

Drain-Source Diode Characteristics and Maximum Ratings

I_S	Maximum Continuous Drain-Source Diode Forward Current	--	--	-9.4	A	
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current	--	--	-37.6	A	
V_{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = -9.4\text{ A}$	--	--	-4.0	V
t_{rr}	Reverse Recovery Time	$V_{GS} = 0\text{ V}, I_S = -11.4\text{ A},$	--	83	--	ns
Q_{rr}	Reverse Recovery Charge	$di_F / dt = 100\text{ A}/\mu\text{s}$ (Note 4)	--	0.26	--	μC

Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. $L = 2.1\text{ mH}, I_{AS} = -9.4\text{ A}, V_{DD} = -25\text{ V}, R_G = 25\ \Omega$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq -11.4\text{ A}, di/dt \leq 300\text{ A}/\mu\text{s}, V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$
4. Pulse Test : Pulse width $\leq 300\ \mu\text{s}$, Duty cycle $\leq 2\%$
5. Essentially independent of operating temperature

Typical Characteristics

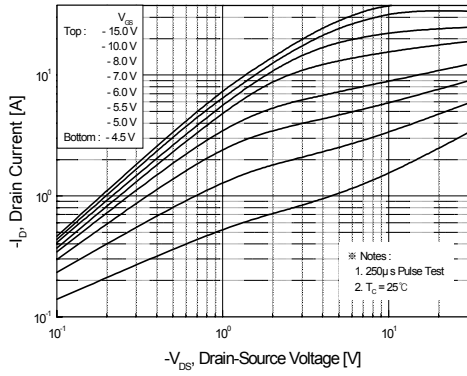


Figure 1. On-Region Characteristics

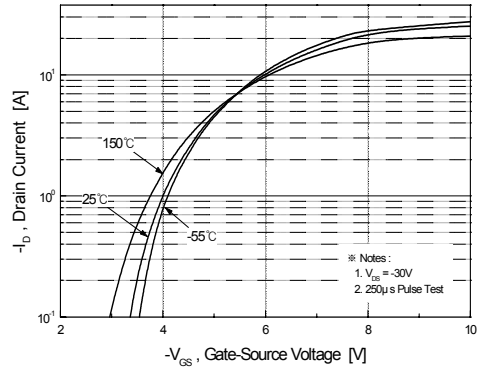


Figure 2. Transfer Characteristics

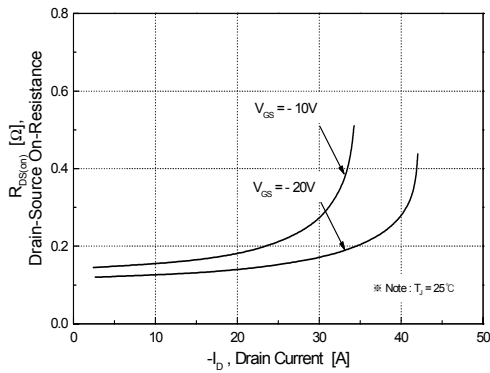


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

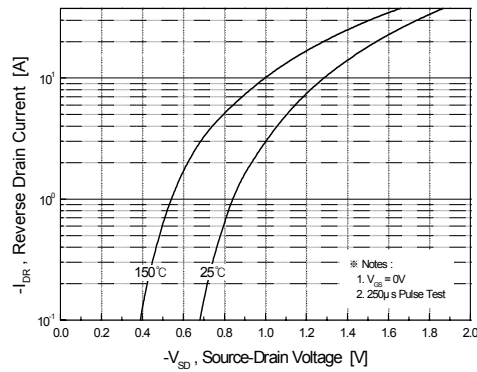


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

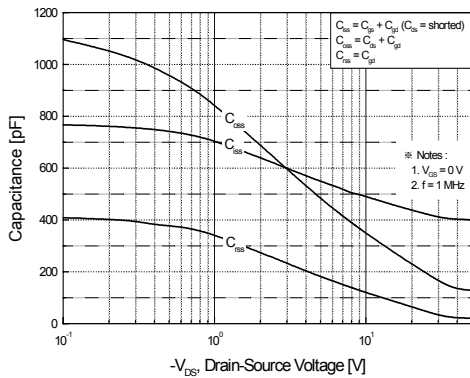


Figure 5. Capacitance Characteristics

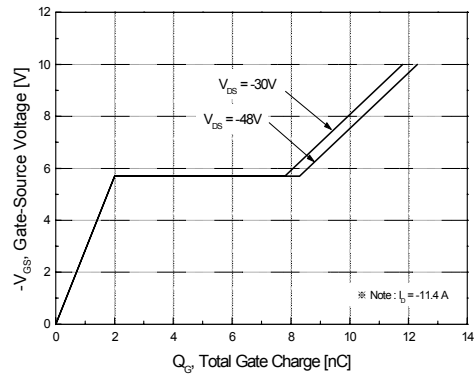


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

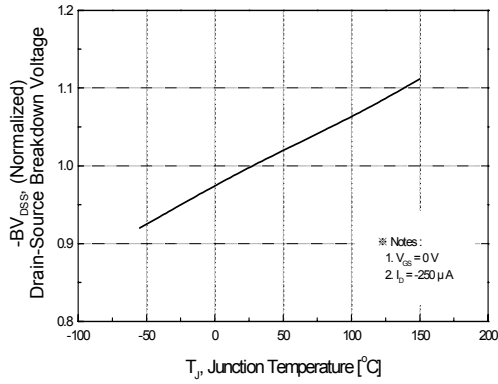


Figure 7. Breakdown Voltage Variation vs. Temperature

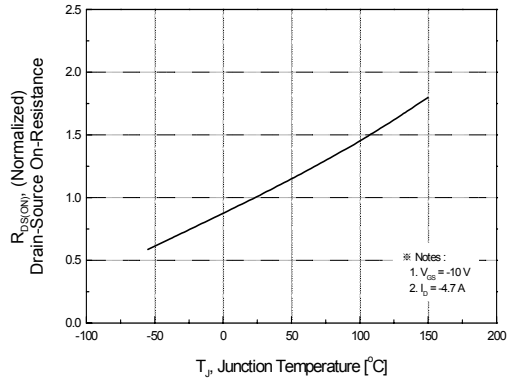


Figure 8. On-Resistance Variation vs. Temperature

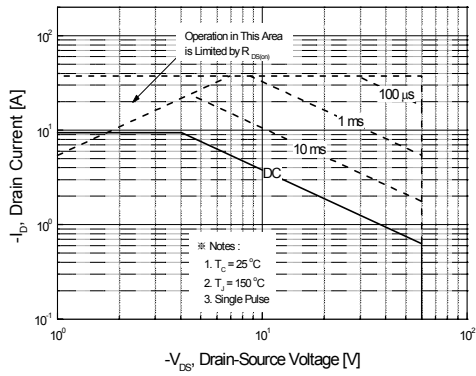


Figure 9. Maximum Safe Operating Area

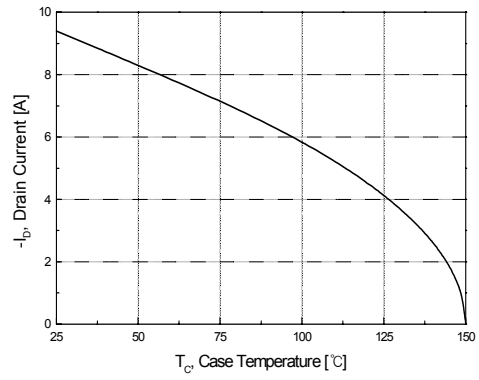


Figure 10. Maximum Drain Current vs. Case Temperature

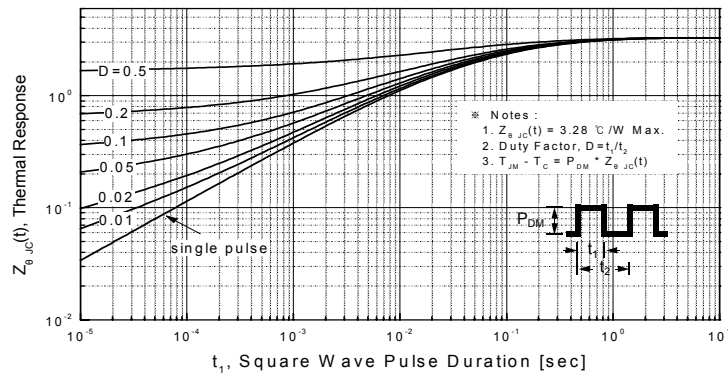
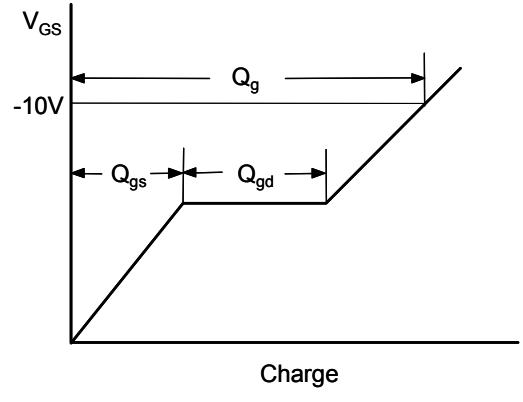
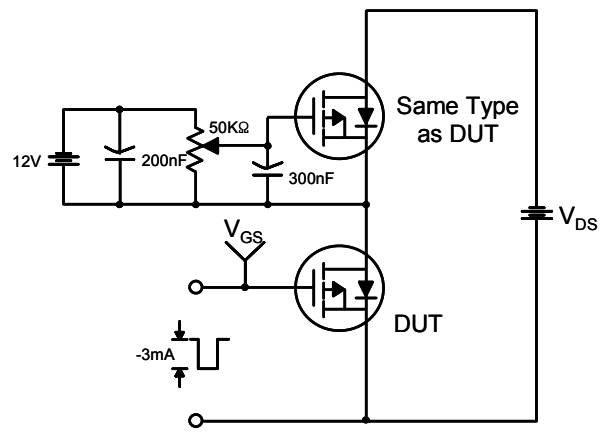
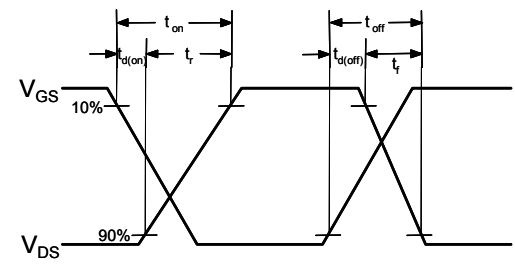
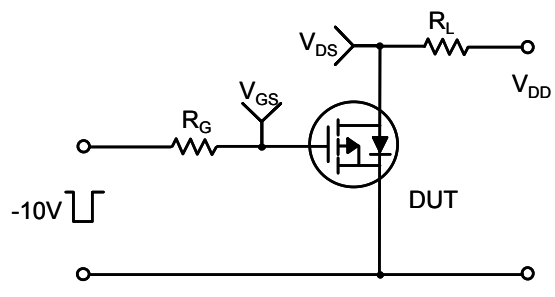


Figure 11. Transient Thermal Response Curve

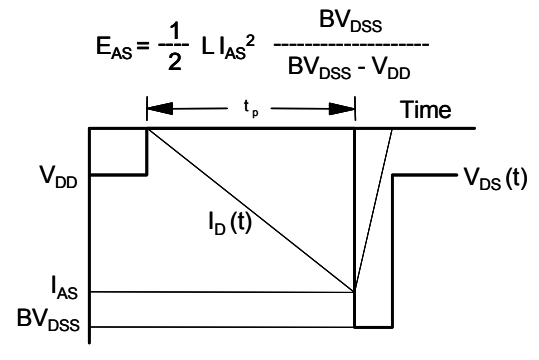
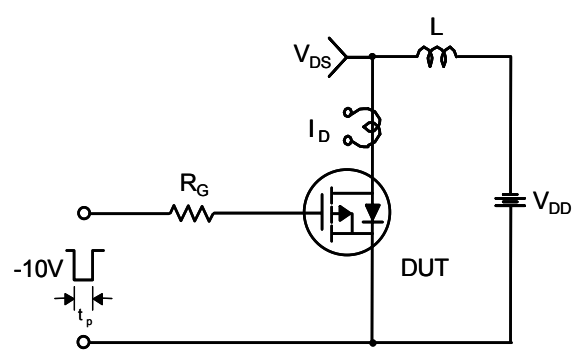
Gate Charge Test Circuit & Waveform



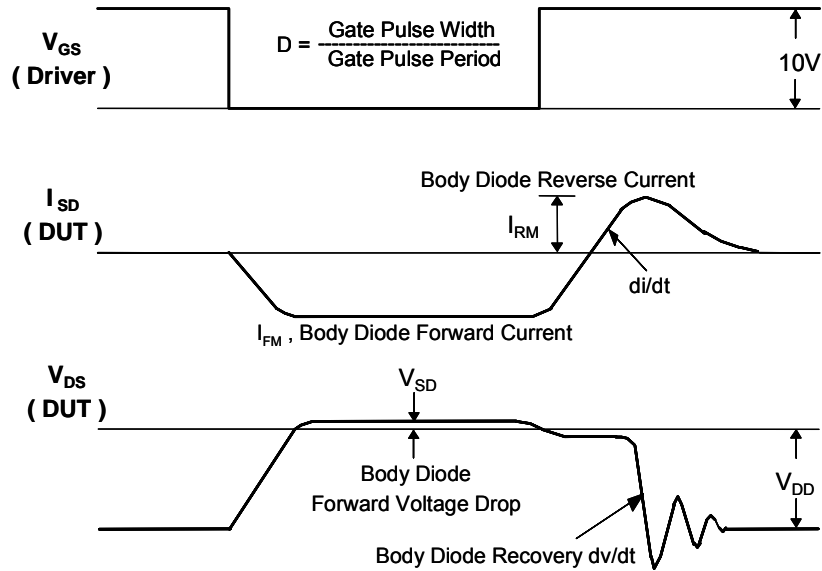
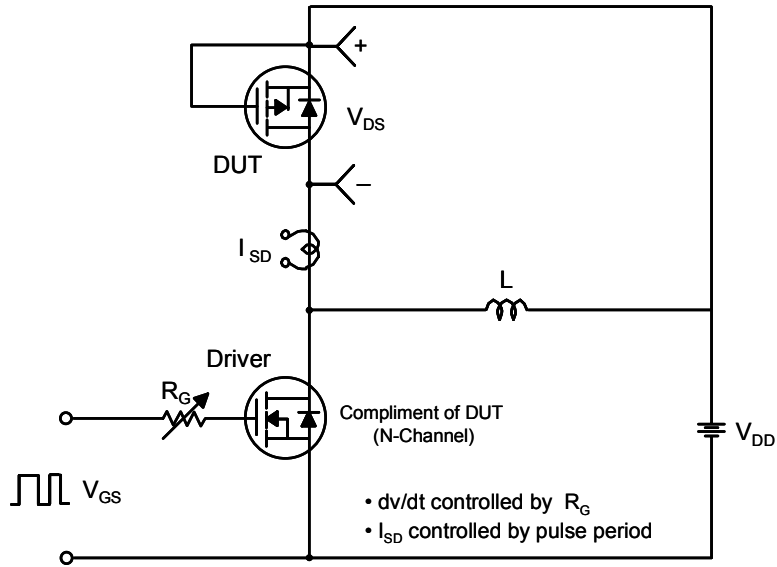
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

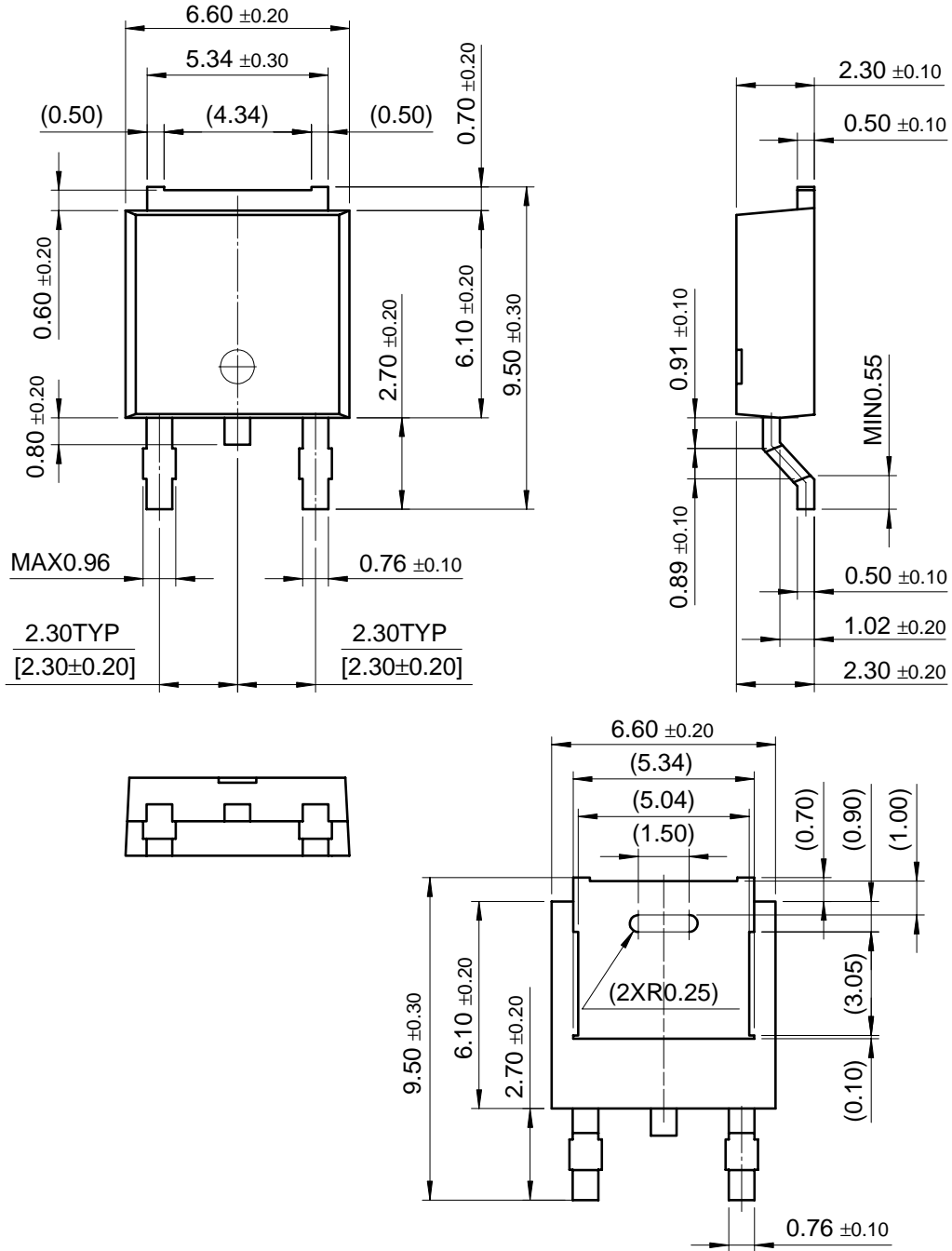


Peak Diode Recovery dv/dt Test Circuit & Waveforms



Package Dimensions

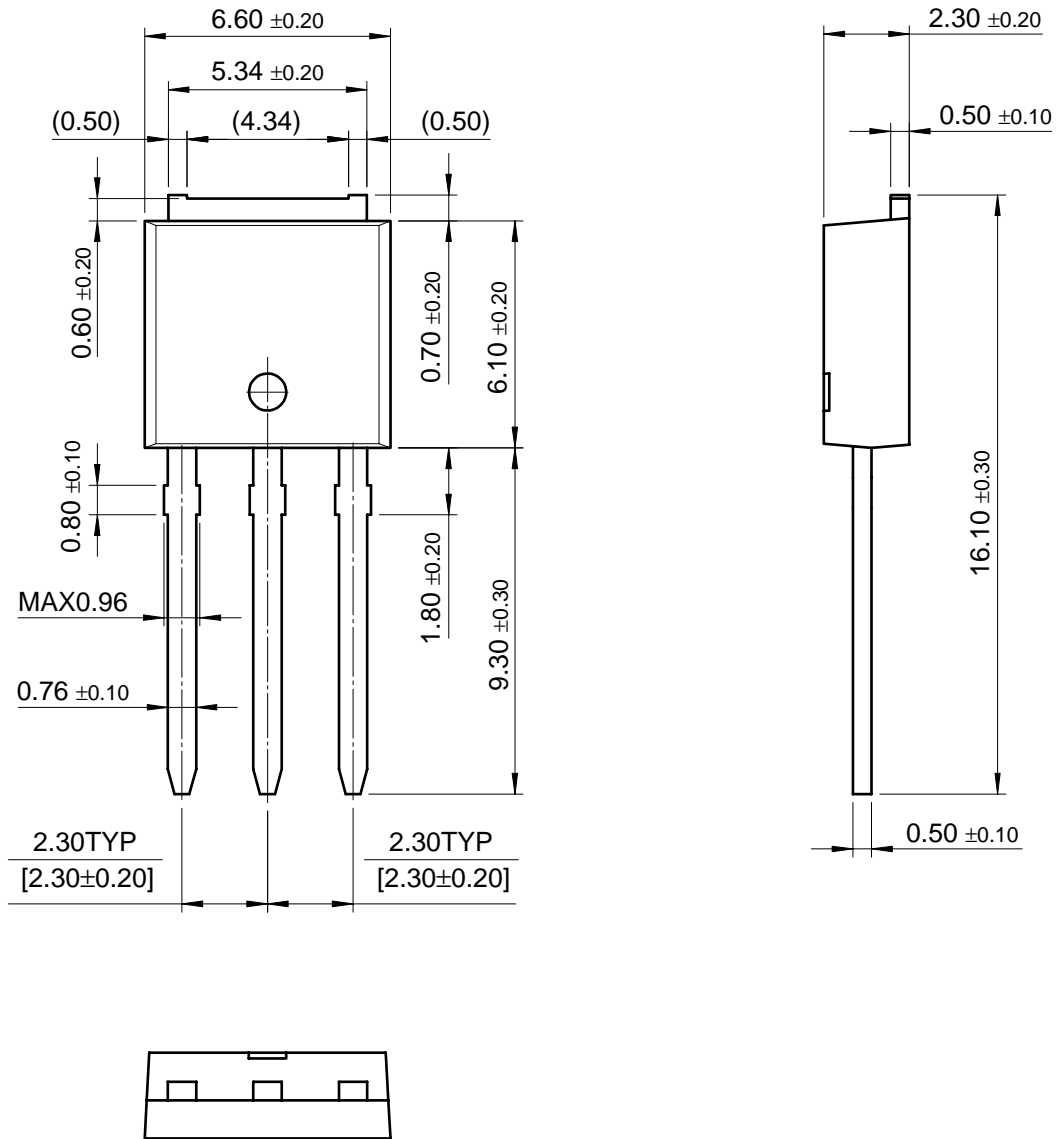
D-PAK



Dimensions in Millimeters

Package Dimensions (Continued)

I-PAK



Dimensions in Millimeters

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Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.

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FQD11P06

60V P-Channel QFET

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General description

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FQD11P06TF	Full Production	 Full Production	\$0.65	TO-252(DPAK)	2	TAPE REEL	Line 1: \$Y (Fairchild logo) &Z (Asm. Plant Code) &4 (4-Digit Date Code) Line 2: FQD Line 3: 11P06
FQD11P06TM	Full Production	 Full Production	\$0.65	TO-252(DPAK)	2	TAPE REEL	Line 1: \$Y (Fairchild logo) &Z (Asm. Plant Code) &4 (4-Digit Date Code) Line 2: FQD Line 3: 11P06
FQD11P06TM_SB82077	Full Production	 Full Production	N/A	TO-252(DPAK)	2	TAPE REEL	Line 1: \$Y (Fairchild logo) &Z (Asm. Plant Code) &4 (4-Digit Date Code) Line 2: FQD Line 3: 11P06

* Fairchild 1,000 piece Budgetary Pricing

** A sample button will appear if the part is available through Fairchild's on-line samples program. If there is no sample button, please contact a [Fairchild distributor](#) to obtain samples



Indicates product with Pb-free second-level interconnect. For more information [click here](#).

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Qualification Support

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